

High Efficiency Fast Response, 2A, 18V Input **Synchronous Step-Down Regulator**

❖ GENERAL DESCRIPTION

AX3811A develops high efficiency synchronous step-down DC-DC converter capable of delivering 2A load current. AX3811A operates over a wide input voltage range from 4.35V to 18V and integrates main switch and synchronous switch with very low $R_{DS(ON)}$ to minimize the conduction loss.

AX3811A adopts the instant PWM architecture to achieve fast transient responses for high step down applications and high efficiency at light loads. In addition, it operates at pseudo-constant frequency of 500 kHz under heavy load conditions to minimize the size of inductor and capacitor.

❖ FEATURES

- Low $R_{DS(ON)}$ for internal switches (top/bottom):140/130 m Ω
- 4.35-18V input voltage range
- 2A load current capability
- Instant PWM architecture to achieve fast transient responses Internal softstart limits the inrush current
- 2% 0.6V reference
- RoHS Compliant and Halogen Free
- Compact package: SOT23-6

Applications

- Set Top Box
- Portable TV
- Access Point Router
- DSL Modem
- LCD TV

❖ ELECTRICAL CHARACTERISTICS

($V_{IN} = 12V$, $V_{OUT} = 1.2V$, $L = 4.7\mu H$, $C_{OUT} = 22\mu F \times 2$, $T_A = 25^\circ C$, $I_{OUT} = 1A$ unless otherwise specified)

Characteristics	Symbol	Conditions	Min	Typ	Max	Units
Input Voltage Range	V_{IN}		4.35	-	18	V
Quiescent Current	I_Q	$I_{OUT}=0$, $V_{FB}=V_{REF} \times 105\%$	-	350		μA
Shutdown Current	I_{SHDN}	EN=0	-	5	10	μA
Feedback Reference Voltage	V_{REF}		0.588	0.6	0.612	V
FB Input Current	I_{FB}	$V_{FB}=V_{IN}$	-50		50	nA
Top FET RON	$R_{DS(ON)1}$		-	0.13	0.15	Ω
Bottom FET RON	$R_{DS(ON)2}$		-	0.12	0.14	Ω
TOP FET Peak Current Limit	$I_{LIM, TOP}$		3	-	3.6	A
Bottom FET Valley Current Limit	$I_{LIM, BOTTOM}$		2	-	2.8	A
EN Rising Threshold	V_{ENH}		1.5	-	-	V
EN Falling Threshold	V_{ENL}		-	-	0.4	V
Input UVLO Threshold	V_{UVLO}		-	-	4.35	V
Min ON Time	-		40	50	100	ns
Min Off Time	-		60	100	150	ns
Soft-start Time	t_{SS}		-	400	-	μS
Thermal Shutdown Temperature	T_{SD}		-	150	-	$^\circ C$
Thermal Shutdown Hysteresis	T_{HYS}		-	15	-	$^\circ C$

Note 1: Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device.

These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2: θ_{JA} is measured in the natural convection at $T_A = 25^\circ C$ on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Pin 2 of SOT-23-6 packages is the case position for θ_{JC} measurement.

Note 3: The device is not guaranteed to function outside its operating conditions.

❖ APPLICATION CIRCUIT

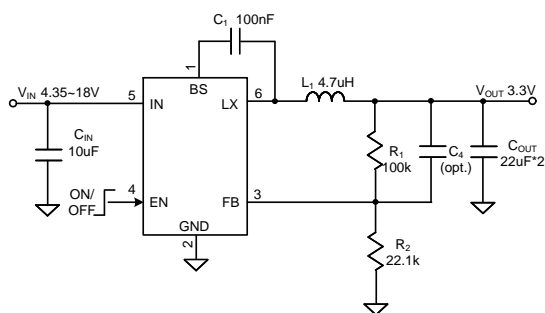


Figure 1. Schematic Diagram

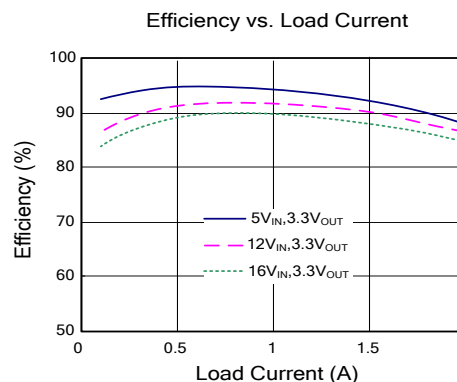


Figure 2. Efficiency Figure

❖ FUNCTION DESCRIPTIONS

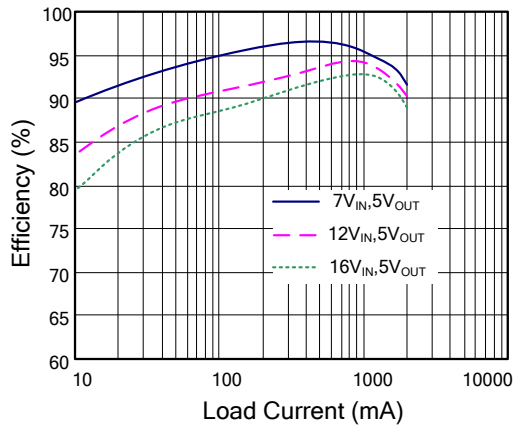
Operation

AX3811A is a synchronous buck regulator IC that integrates the PWM control, top and bottom switches on the same die to minimize the switching transition loss and conduction loss. With ultra-low $R_{ds(on)}$ power switches and proprietary PWM control, this regulator IC can achieve the highest efficiency and the highest switch frequency simultaneously to minimize the external inductor and capacitor size, and thus achieving the minimum solution footprint.

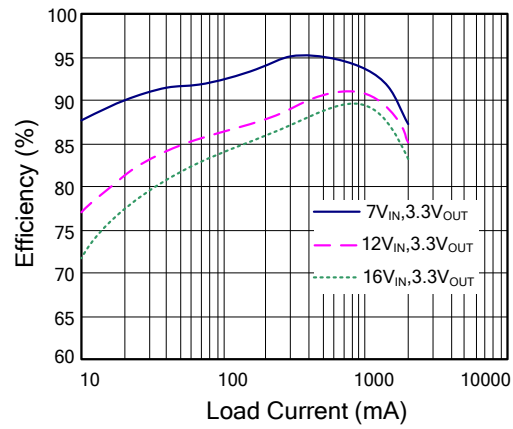
AX3811A provides protection functions such as cycle by cycle current limiting and thermal shutdown protection. AX3811A will sense the output voltage conditions for the fault protection.

❖ TYPICAL CHARACTERISTICS

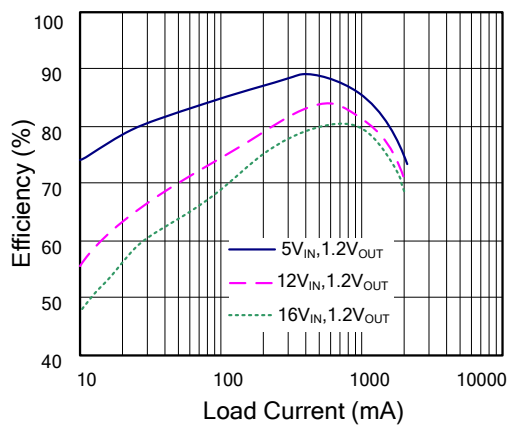
Efficiency vs. Load Current



Efficiency vs. Load Current

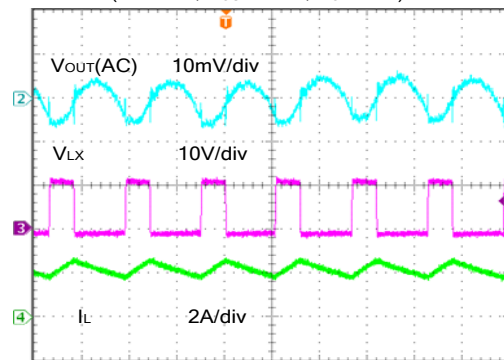


Efficiency vs. Load Current



Output Ripple

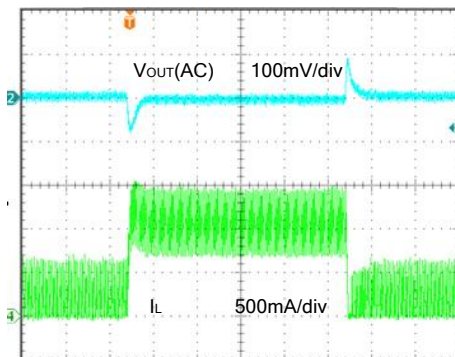
($V_{IN}=12V, V_{OUT}=3.3V, I_{LOAD}=2A$)



Time (1us/div)

Load Transient

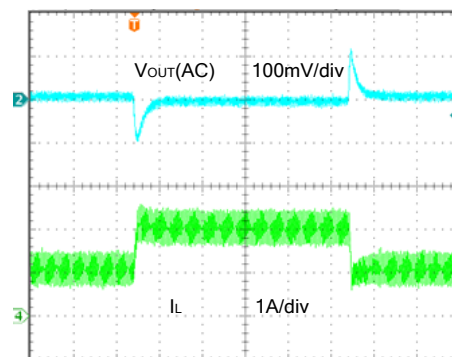
($V_{IN}=12V, V_{OUT}=3.3V, I_{LOAD}=0.2-1A$)



Time (40us/div)

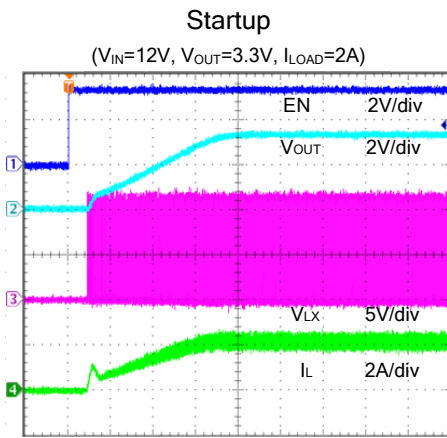
Load Transient

($V_{IN}=12V, V_{OUT}=3.3V, I_{LOAD}=1-2A$)

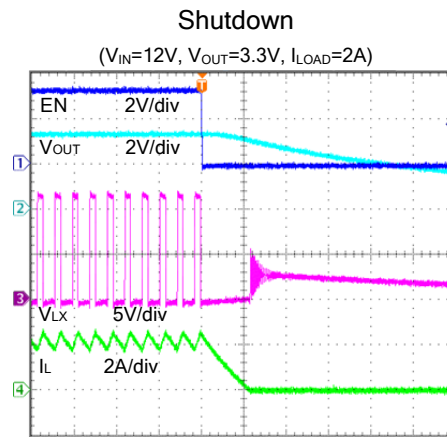


Time (40us/div)

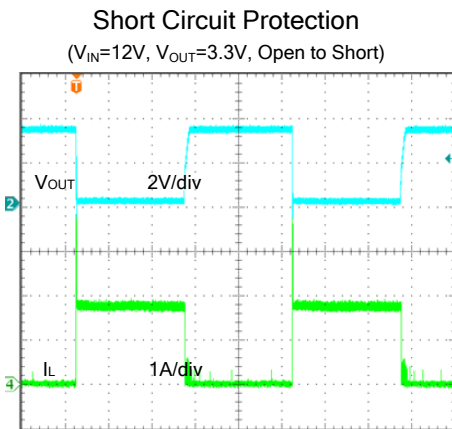
❖ TYPICAL CHARACTERISTICS (COUNTINOUS)



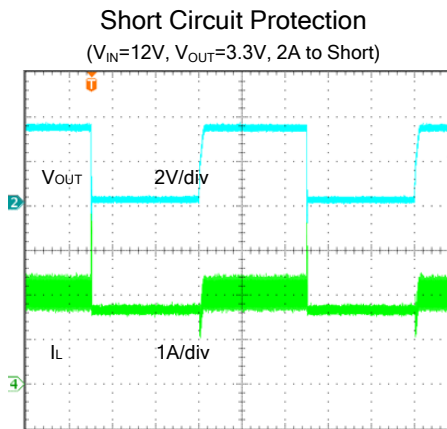
Time (100us/div)



Time (4us/div)



Time (2ms/div)



Time (2ms/div)

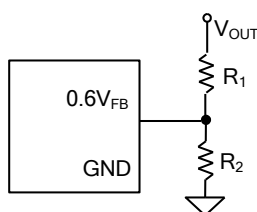
❖ APPLICATION INFORMATION

Because of the high integration in the AX3811A IC, the application circuit based on this regulator IC is rather simple. Only input capacitor C_{IN} , output capacitor C_{OUT} , output inductor L and feedback resistors (R1 and R2) need to be selected for the targeted applications specifications.

Feedback resistor dividers R1 and R2:

Choose R1 and R2 to program the proper output voltage. To minimize the power consumption under light loads, it is desirable to choose large resistance values for both R1 and R2. A value of between 10k Ω and 100k Ω is highly recommended for both resistors. If V_{out} is 3.3V, R1=100k is chosen, then using following equation, R2 can be calculated to be 22.1k:

$$R_2 = \frac{0.6V}{V_{OUT} - 0.6V} R_1$$



Input capacitor C_{IN} :

The ripple current through input capacitor is calculated as:

$$I_{CIN_RMS} = I_{OUT} \cdot \sqrt{D(1-D)}$$

To minimize the potential noise problem, place a typical X5R or better grade ceramic capacitor really close to the IN and GND pins. Care should be taken to minimize the loop area formed by C_{IN} , and IN/GND pins. In this case, a 10uF low ESR ceramic capacitor is recommended.

Output capacitor C_{OUT} :

The output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For the best performance, it is recommended to use X5R or better grade ceramic capacitor greater than 22uF capacitance.

Output inductor L:

There are several considerations in choosing this inductor.

- (1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum output current. The inductance is calculated as:

$$L = \frac{V_{OUT} (1 - V_{OUT}/V_{IN,MAX})}{f_{SW} \times I_{OUT,MAX} \times 40\%}$$

where f_{sw} is the switching frequency and $I_{OUT,MAX}$ is the maximum load current.

The AX3811A regulator IC is quite tolerant of different ripple current amplitude. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

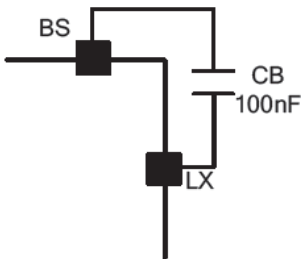
- (2) The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{SAT,MIN} > I_{OUT,MAX} + \frac{V_{OUT} (1 - V_{OUT}/V_{IN,MAX})}{2 \cdot f_{SW} \cdot L}$$

- (3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with $DCR < 50m\Omega$ to achieve a good overall efficiency.

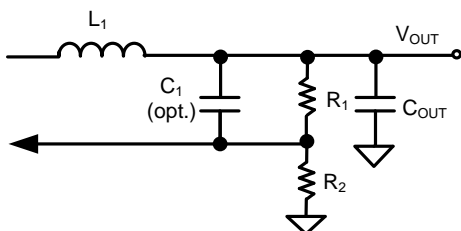
External Bootstrap Cap

This capacitor provides the gate driver voltage for internal high side MOSEFET. A 100nF low ESR ceramic capacitor connected between BS pin and LX pin is recommended.



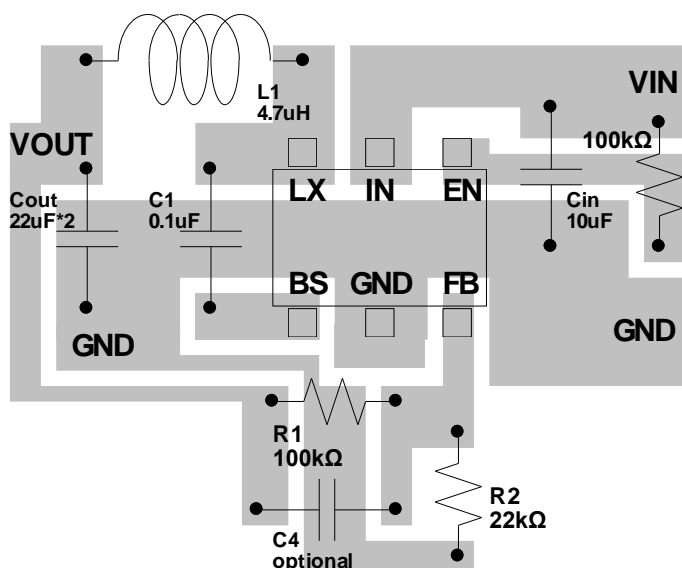
Load Transient Considerations:

The AX3811A regulator IC integrates the compensation components to achieve good stability and fast transient responses. In some applications, adding a 22pF ceramic cap in parallel with R1 may further speed up the load transient responses and is thus recommended for applications with large load transient step requirements.



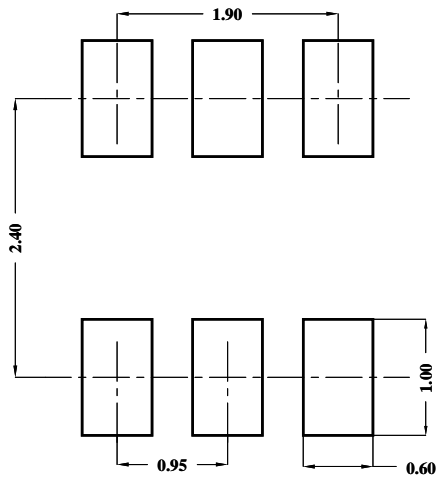
Layout Design:

The layout design of AX3811A regulator is relatively simple. For the best efficiency and minimum noise problem, we should place the following components close to the IC: C_{IN}, L, R1 and R2.

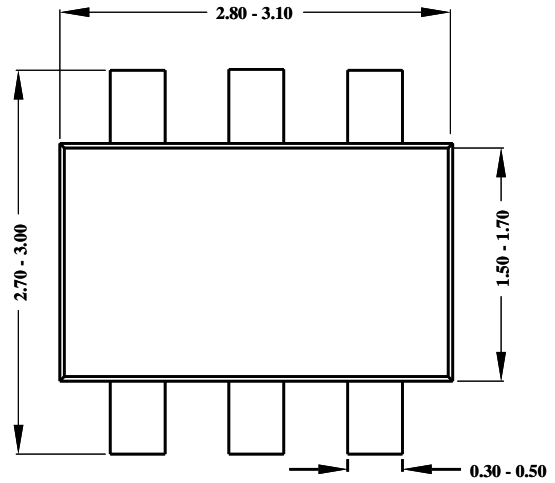


- (1) It is desirable to maximize the PCB copper area connecting to GND pin to achieve the best thermal and noise performance. If the board space allowed, a ground plane is highly desirable.
- (2) C_{IN} must be close to pins IN and GND. The loop area formed by C_{IN} and GND must be minimized.
- (3) The PCB copper area associated with LX pin must be minimized to avoid the potential noise problem.
- (4) The components R1 and R2, and the trace connecting to the FB pin must NOT be adjacent to the LX net on the PCB layout to avoid the noise problem.
- (5) If the system chip interfacing with the EN pin has a high impedance state at shutdown mode and the IN pin is connected directly to a power source such as a Li-Ion battery, it is desirable to add a pull down 1Mohm resistor between the EN and GND pins to prevent the noise from falsely turning on the regulator at shutdown mode.

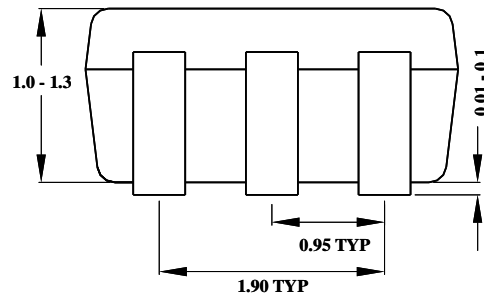
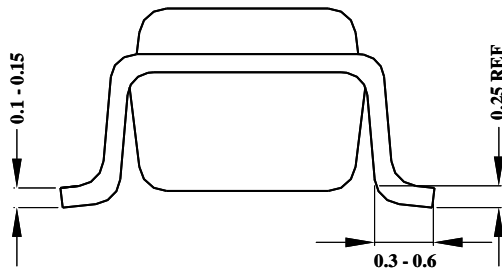
❖ PACKAGE OUTLINES



Recommended Pad Layout



Top View



Notes: All dimension in MM
 All dimension don't not include mold flash and metal burr